

5. (Twice Amended) Thermosettable adhesive according to claim 1, wherein the adhesive is a reaction product formed by photopolymerization of an adhesive precursor comprising:

B² (i) from about 25 to 60 wt.% of a photopolymerizable, optionally partly prepolymerized mixture comprising at least one acrylic acid ester of a non-tertiary alcohol, and at least one reinforcing, copolymerizable monomer;

(ii) from about 8 to 60 wt.% of one or more compounds selected from epoxy monomers, epoxy oligomers, epoxy resins, or combinations thereof, wherein the one or more compounds contain no photopolymerizable groups;

(iii) from 0 to 15 wt.% of one or more additional thermoformable polymers selected from polyvinylacetate, poly(ethylene vinyl acetate), polyacetals, polyesters, poly(caprolactones), or combinations thereof;

(iv) from about 0.1 to 10 wt.% of a heat-activatable curing system for the epoxy component (ii);

(v) from about 0.005 to 3 wt.% of a photoinitiator for the acrylate components (i); and

(vi) from about 0.1 to 20 wt.% of one or more compounds selected from hydroxides of Al, Mg and Zr; hydroxyoxides of Al, Mg and Zr; or combinations thereof;

wherein all weight percentages are based on the total weight of the thermosettable adhesive.

B³ 6. (Amended) Thermosettable adhesive according to claim 5, wherein the acrylate component (i) further comprises at least one hydroxy-substituted acrylic ester of a non-tertiary alcohol in addition to the at least one acrylic ester of a non-tertiary alcohol.

B⁴ 7. (Twice Amended) Thermosettable adhesive according to claim 1 formed by extrusion of a mixture comprising:

(i) from about 2 to 80 wt.% of one or more polyesters;

(ii) from about 5 to 80 wt.% of one or more compounds selected from epoxy monomers, epoxy oligomers, epoxy resins, or combinations thereof;

(iii) from 0 to 15 wt. % of one or more additional thermoformable polymers selected from polyacrylate, polyvinylacetate, poly(ethylene vinyl acetate), polyacetals, poly(caprolactones), or combinations thereof;

(iv) an effective amount of one or more heat-activatable or one or more photoactivatable curing systems, or combinations thereof, for the epoxy component (ii); and

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(v) from about 0.1 to 20 wt.% of one or more compounds selected from hydroxides of Al, Mg and Zr; hydroxyoxides of Al, Mg and Zr; or combinations thereof, wherein an onset temperature of a curing reaction of the epoxy component (ii) is higher than an extrusion temperature and wherein all weight percentages are based on the total weight of the thermosettable adhesive.

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10. (Amended) A thermosettable adhesive comprising:

- (i) a thermosettable polymer selected from the group consisting of epoxy resins, epoxy monomers, and epoxy oligomers;
- (ii) a thermoformable polymer selected from polyacrylate homopolymers and copolymers;
- (iii) an effective amount of a curing agent for the thermosettable polymer; and
- (iv) 0.1 to 20 weight percent of one or more compounds selected from the group consisting of aluminum hydroxides and aluminum hydroxyoxides, based on a total weight of the thermosettable adhesive.

[Please add the following new claims:

11. (New) Thermosettable adhesive according to claim 1, wherein the one or more compounds comprise hydroxides of Al; hydroxyoxides of Al; or combinations thereof.

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12. (New) Thermosettable adhesive according to claim 1, wherein the one or more compounds comprise hydroxyoxides of Al, Mg and Zr.

13. (New) Thermosettable adhesive according to claim 1, wherein the one or more compounds are present at a weight percent of at least 2.5 wt% based on the total weight of the thermosettable adhesive.

14. (New) Thermosettable adhesive according to claim 1, wherein the at least one reinforcing, copolymerizable monomer comprises isobornyl acrylate, N-vinyl pyrrolidone, N-vinyl caprolactam, N-vinyl piperidine, N,N-dimethylacrylamide, acrylonitrile, or combinations thereof.

15. (New) Thermosettable adhesive according to claim 10, wherein the one or more compounds are present at a weight percent of at least 2.5 wt% based on the total weight of the thermosettable adhesive.

16. (New) Thermosettable adhesive according to claim 10, wherein the one or more compounds comprise aluminum hydroxyoxides.

17. (New) A thermosettable adhesive comprising a reaction product formed by photopolymerization of an adhesive precursor comprising:

(i) from about 25 to 60 wt.% of a photopolymerizable, optionally partly prepolymerized mixture comprising at least one acrylic acid ester of a non-tertiary alcohol, and at least one reinforcing, copolymerizable monomer;

(ii) from about 8 to 60 wt.% of one or more first compounds selected from epoxy monomers, epoxy oligomers, epoxy resins, or combinations thereof, wherein the one or more first compounds contain no photopolymerizable groups;

(iii) from 0 to 15 wt.% of one or more additional thermoformable polymers selected from polyvinylacetate, poly(ethylene vinyl acetate), polyacetals, polyesters, poly(caprolactones), or combinations thereof;

(iv) from about 0.1 to 10 wt.% of a heat-activatable curing system for the epoxy component (ii);

(v) from about 0.005 to 3 wt.% of a photoinitiator for the acrylate components (i); and

(vi) from about 0.1 to 20 wt.% of one or more second compounds selected from hydroxides of Al; hydroxyoxides of Al; or combinations thereof;

wherein all weight percentages are based on the total weight of the thermosettable adhesive.

18. (New) The thermosettable adhesive according to claim 17, wherein the one or more second compounds comprise aluminum hydroxyoxides.

19. (New) The thermosettable adhesive according to claim 17, wherein the one or more second compounds are present at a weight percent of at least 2.5 wt% based on the total weight of the thermosettable adhesive.